

HAT2187WP

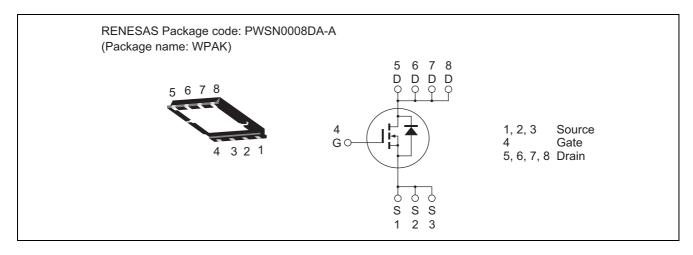
Silicon N Channel Power MOS FET Power Switching

REJ03G0535-0500 Rev.5.00 Sep.02,2005

Features

- Low on-resistance
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	200	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I _D	17	А
Drain peak current	I _{D (pulse)} Note1	34	А
Body-drain diode reverse drain current	I _{DR}	17	А
Body-drain diode reverse drain peak current	I _{DR} (pulse)	34	А
Avalanche current	I _{AP} Note3	17	А
Avalanche energy	E _{AR} Note3	19.2	mJ
Channel dissipation	Pch Note2	30	W
Channel to case thermal impedance	θch-c	4.17	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at Tc = 25°C

3. STch = 25° C, Tch $\leq 150^{\circ}$ C

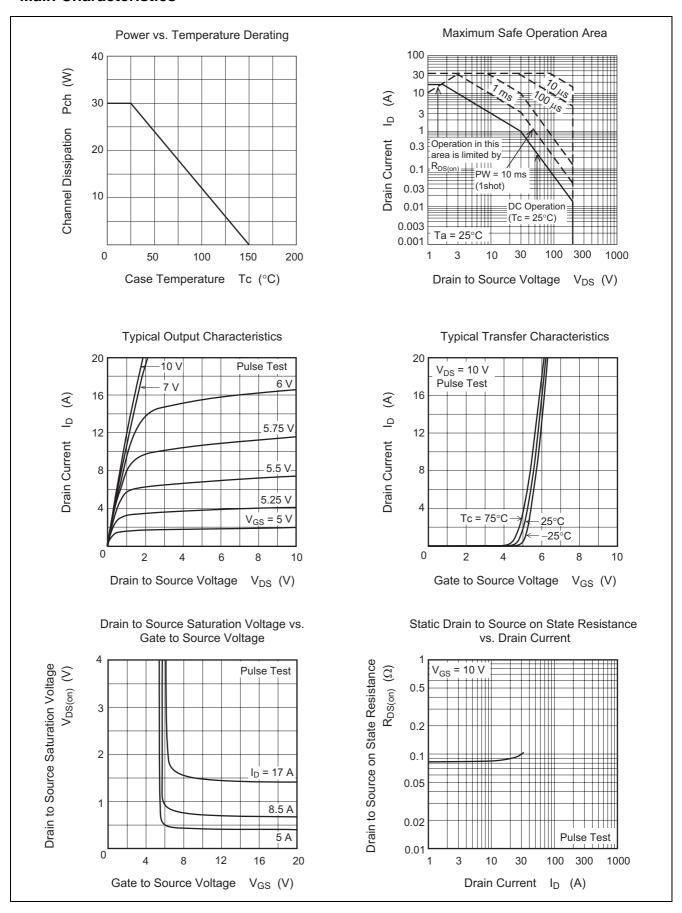
Electrical Characteristics

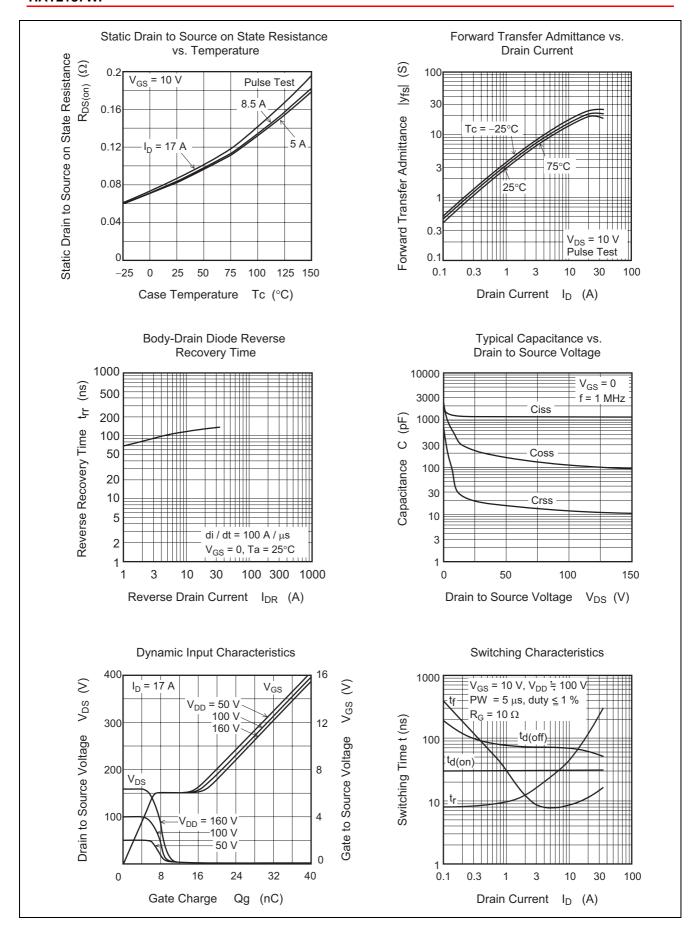
 $(Ta = 25^{\circ}C)$

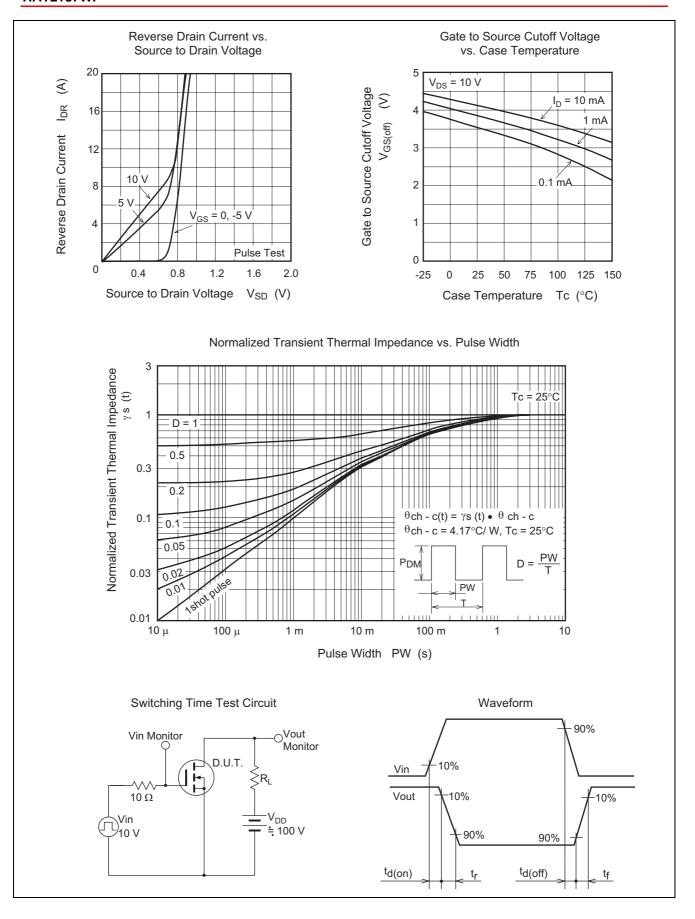
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	200	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	yfs	8	14	_	S	$I_D = 8.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Static drain to source on state	R _{DS(on)}	_	0.084	0.094	Ω	$I_D = 8.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
resistance						
Input capacitance	Ciss		1200		pF	V _{DS} = 25 V
Output capacitance	Coss	_	220	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	19	_	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	_	31	_	ns	I _D = 8.5 A
Rise time	t _r	_	37	_	ns	V _{GS} = 10 V
Turn-off delay time	t _{d(off)}	_	69	_	ns	$R_L = 11.8 \Omega$
Fall time	t _f	_	8	_	ns	$Rg = 10 \Omega$
Total gate charge	Qg	_	26	_	nC	V _{DD} = 160 V
Gate to Source charge	Qgs	_	7	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	10	_	nC	I _D = 17 A
Body-drain diode forward voltage	V_{DF}	_	0.9	1.4	V	$I_F = 17 \text{ A}, V_{GS} = 0^{\text{Note4}}$
Body-drain diode reverse recovery time	trr	_	130	_	ns	$I_F = 17 \text{ A}, V_{GS} = 0$
						diF/dt = 100 A/μs

Notes: 4. Pulse test

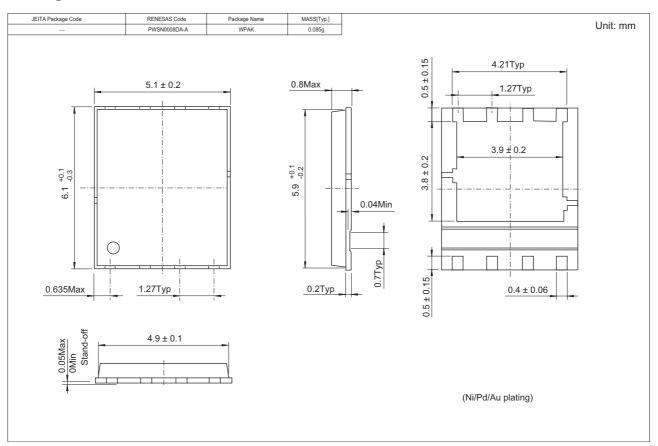
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2187WP-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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